



S-575  
SK326US

Rev. 1-10-03

Effective March 1998

## DECLARATION AND POWER OF ATTORNEY FOR U.S. PATENT APPLICATION

☐ Original ☐ Supplemental ☐ Substitute ☒ PCT ☐ DESIGN

As a below named inventor, I hereby declare that: my residence, post office address and citizenship are as stated below next to my name; that I verily believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural inventors are named below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

Title: METHOD FOR MANUFACTURING SEMICONDUCTOR CHIP

of which is described and claimed in:

☐ the attached specification, or

☐ the specification in application Serial No. \_\_\_\_\_, filed \_\_\_\_\_, and with amendments through \_\_\_\_\_, or

☒ the specification in International Application No. PCT/JP2004/017955, filed December 2, 2004, and as amended on \_\_\_\_\_ (if applicable).

I hereby state that I have reviewed and understand the content of the above-identified specification, including the claims, as amended by any amendment(s) referred to above.

I acknowledge my duty to disclose to the Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56.

I hereby claim priority benefits under Title 35, United States Code, §119 (and §172 if this application is for a Design) of any application(s) for patent or inventor's certificate listed below and have also identified below any application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

COUNTRY	APPLICATION NO.	DATE OF FILING	PRIORITY CLAIMED
Japan	2003-403431	December 2, 2003	YES
Japan	2004-107584	March 31, 2004	YES
Japan	2004-282807	September 28, 2004	YES
Japan	2004-282808	September 28, 2004	YES

I hereby claim the benefit under Title 35, United States Code §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code §112, I acknowledge the duty to disclose information material to patentability as defined in Title 37, Code of Federal Regulations, §1.56 which occurred between the filing date of the prior application and the national or PCT international filing date of this application:

APPLICATION SERIAL NO.	U.S. FILING DATE	STATUS: PATENTED, PENDING, ABANDONED

And I hereby appoint Michael R. Davis, Reg. No. 25,134; Matthew M. Jacob, Reg. No. 25,154; Warren M. Cheek, Jr., Reg. No. 33,367; Nils Pedersen, Reg. No. 33,145; Charles R. Watts, Reg. No. 33,142; Michael S. Huppert, Reg. No. 40,268; Jeffrey R. Filipek, Reg. No. 41,471; and Douglas W. Hahm, Reg. No. 44,142, who together constitute the firm of WENDEROTH, LIND & PONACK, L.L.P., as well as any other attorneys and agents associated with Customer No. 000513, to prosecute this application and to transact all business in the U.S. Patent and Trademark Office connected therewith.

S-575  
SK32545

I hereby authorize the U.S. attorneys and agents named herein to accept and follow instructions from YASUTOMI & ASSOCIATES as to any action to be taken in the U.S. Patent and Trademark Office regarding this application without direct communication between the U.S. attorneys and myself. In the event of a change in the persons from whom instructions may be taken, the U.S. attorneys named herein will be so notified by me.

Direct Correspondence to:   <p style="text-align: center;">CUSTOMER NO. <b>000513</b></p>	Direct Telephone Calls to:  WENDEROTH, LIND & PONACK, L.L.P. 2033 "K" Street, N.W., Suite 800 Washington, D.C. 20006-1021  Phone: (202) 721-8200 Fax: (202) 721-8250
--	---

Full Name of First Inventor	FAMILY NAME SUGITA	FIRST GIVEN NAME Daihei	SECOND GIVEN NAME
Residence & Citizenship	CITY Saitama	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Sekisui Chemical Co., Ltd., 3535, Kurohama, Hasuda-shi, Saitama 349-0198 Japan		
Full Name of Second Inventor	FAMILY NAME FUKUOKA	FIRST GIVEN NAME Masateru	SECOND GIVEN NAME
Residence & Citizenship	CITY Osaka	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Sekisui Chemical Co., Ltd., 2-1, Hyakuyama, Shimamotocho, Mishima-gun, Osaka 618-8589 Japan		
Full Name of Third Inventor	FAMILY NAME HATAI	FIRST GIVEN NAME Munehiro	SECOND GIVEN NAME
Residence & Citizenship	CITY Osaka	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Sekisui Chemical Co., Ltd., 2-1, Hyakuyama, Shimamotocho, Mishima-gun, Osaka 618-8589 Japan		
Full Name of Fourth Inventor	FAMILY NAME HAYASHI	FIRST GIVEN NAME Satoshi	SECOND GIVEN NAME
Residence & Citizenship	CITY Osaka	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS CITY STATE OR COUNTRY ZIP CODE c/o Sekisui Chemical Co., Ltd., 2-1, Hyakuyama, Shimamotocho, Mishima-gun, Osaka 618-8589 Japan		

Full Name of Fifth Inventor	FAMILY NAME SHIMOMURA	FIRST GIVEN NAME Kazuhiro	SECOND GIVEN NAME
Residence & Citizenship	CITY Saitama	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS c/o Sekisui Chemical Co., Ltd., 3535, Kurohama, Hasuda-shi, Saitama 349-0198 Japan	CITY	STATE OR COUNTRY ZIP CODE
Full Name of Sixth Inventor	FAMILY NAME KITAJIMA	FIRST GIVEN NAME Yoshikazu	SECOND GIVEN NAME
Residence & Citizenship	CITY Saitama	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS c/o Sekisui Chemical Co., Ltd., 3535, Kurohama, Hasuda-shi, Saitama 349-0198 Japan	CITY	STATE OR COUNTRY ZIP CODE
Full Name of Seventh Inventor	FAMILY NAME OYAMA	FIRST GIVEN NAME Yasuhiko	SECOND GIVEN NAME
Residence & Citizenship	CITY Tokyo	STATE OR COUNTRY Japan	COUNTRY OF CITIZENSHIP Japan
Post Office Address	ADDRESS c/o Sekisui Chemical Co., Ltd., 3-17, Toranomom 2-chome, Minato-ku, Tokyo 105-8450 Japan	CITY	STATE OR COUNTRY ZIP CODE

I further declare that all statements made herein of my own knowledge are true, and that all statements on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

1st Inventor Daihei Sugita Date JUN. - 5. 2006  
Daihei SUGITA  
2nd Inventor Masateru Fukuoka Date JUN. - 5. 2006  
Masateru FUKUOKA  
3rd Inventor Munehiro Hatai Date JUN. - 5. 2006  
Munehiro HATAI  
4th Inventor Satoshi Hayashi Date JUN. - 5. 2006  
Satoshi HAYASHI  
5th Inventor Kazuhiro Shimomura Date JUN. - 5. 2006  
Kazuhiro SHIMOMURA  
6th Inventor Yoshikazu Kitajima Date JUN. - 5. 2006  
Yoshikazu KITAJIMA  
7th Inventor Yasuhiko Oyama Date JUN. - 5. 2006  
Yasuhiko OYAMA

The above application may be more particularly identified as follows:

U.S. Application Serial No. \_\_\_\_\_ Filing Date \_\_\_\_\_

Applicant Reference Number SK326US Atty Docket No. 2006 0490A

Title of Invention METHOD FOR MANUFACTURING SEMICONDUCTOR CHIP